Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Drain-to-Source Voltage (V_{DS})	415	V
Gate-to-Source Voltage (V_{GS})	±20	V
Total Package Dissipation	2.5	W
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @25ºC (Unless Otherwise Specified)

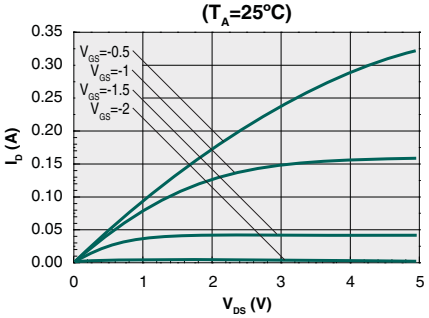
Parameter	Symbol	Conditions	Min	Typ	Max	Units
Gate-to-Source Off Voltage	$V_{GS(off)}$	I_D= 2µA, V_{DS}=10V, V_{DS}=100V	-3.6		-2.0	V
Drain-to-Source Leakage Current	$I_{DS(off)}$	V_{GS}= -5V, V_{DS}=250V	-	-	20	nA
		V_{GS}= -5V, V_{DS}=415V	-	-	1	µA
Drain Current	I_D	V_{GS}= -2.7V, V_{DS}=5V, V_{DS}=50V	-	-	5	mA
		V_{GS}= -0.57V, V_{DS}=5V	130	-	-	mA
On Resistance	$R_{DS(on)}$	V_{GS}= -0.35V, I_{DS}=50mA	-	8	14	Ω
Gate Leakage Current	I_{GSS}	V_{GS}=10V, V_{GS}=-10V	-	-	0.1	µA
Gate Capacitance	C_{ISS}	V_{DS}= V_{GS}=0V	-	-	300	pF

Thermal Characteristics

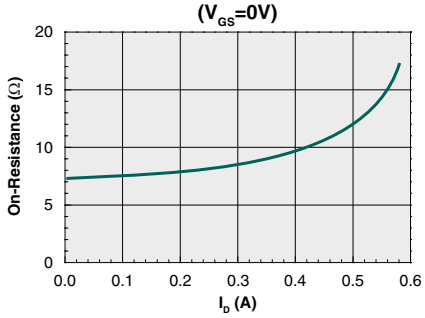
Parameter	Symbol	Conditions	Min	Typ	Max	Units
Thermal Resistance	$R_{\theta JC}$	-	-	-	14	°C/W

Performance Data*

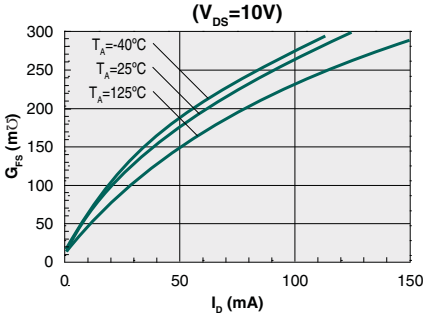
Output Characteristics (T_A=25°C)



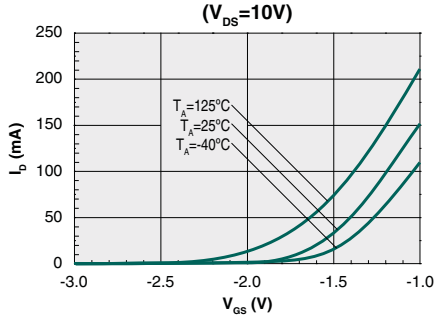
On-Resistance vs. Drain Current (V_{GS}=0V)



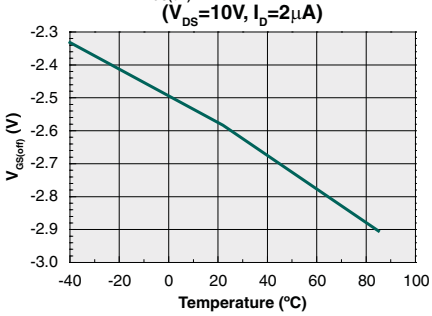
Transconductance vs Drain Current (V_{DS}=10V)



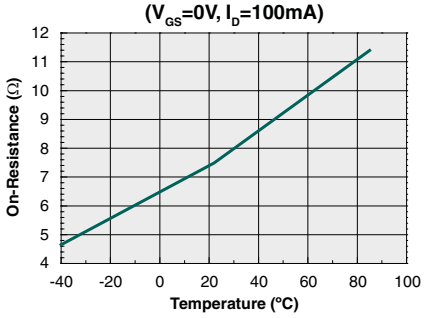
Transfer Characteristics (V_{DS}=10V)



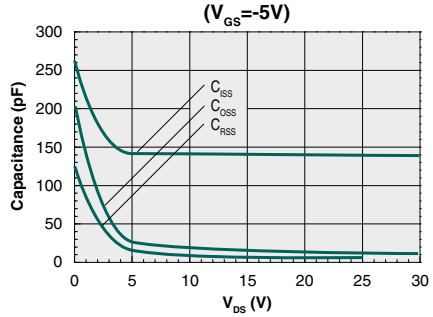
$V_{GS(off)}$ vs. Temperature (V_{DS}=10V, I_D=2μA)



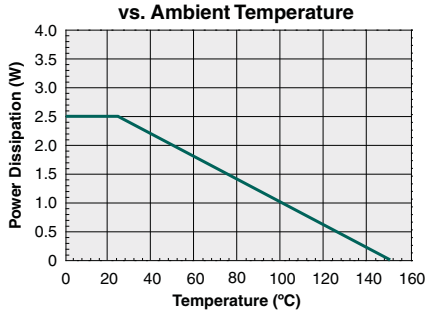
On-Resistance vs. Temperature (V_{GS}=0V, I_D=100mA)



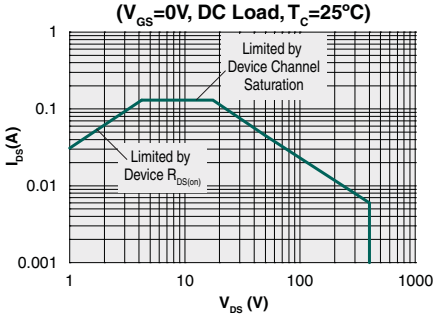
Capacitance vs. Drain-Source Voltage (V_{GS}=-5V)



Power Dissipation vs. Ambient Temperature



Forward Safe Operating Bias (V_{GS}=0V, DC Load, T_C=25°C)



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC5603C	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

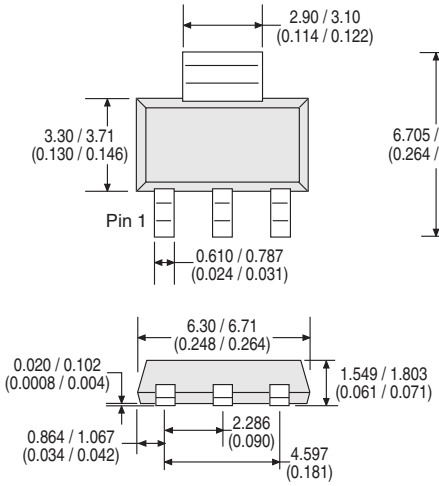
Device	Maximum Temperature x Time
CPC5603C	260°C for 30 seconds

Board Wash

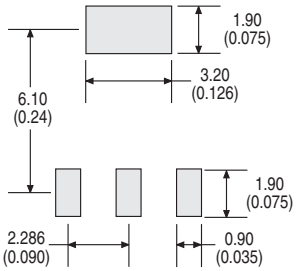
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable, and the use of a short drying bake may be necessary. Chlorine-based or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

MECHANICAL DIMENSIONS

CPC5603C

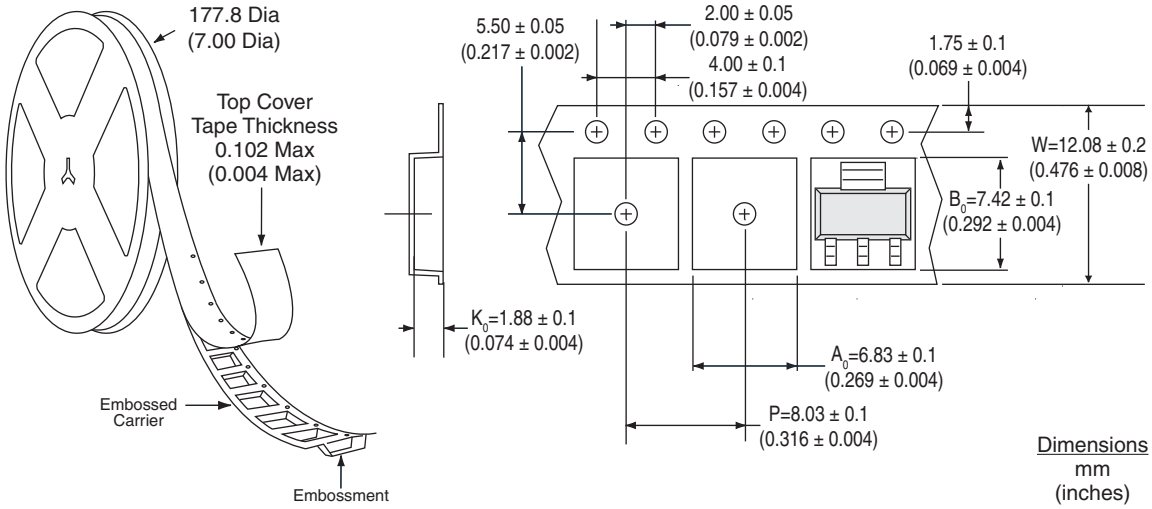


PCB Land Pattern



Dimensions
mm MIN / mm MAX
(inches MIN / inches MAX)

CPC5603CTR Tape & Reel



Dimensions
mm
(inches)

For additional information please visit our website at: www.ixysic.com

Specification: DS-CPC5603-R07

5/10/2013